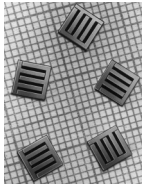


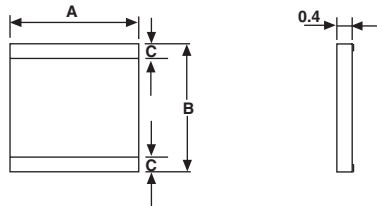
Current Sensing Bondable Chip Resistors



This thin film chip resistor fits applications as force balance scales, E beam deflection systems, switching power supplies, etc... all rely on current sensors to feed back and control the current.

Gold pads are compatible with thermosonic or ultrasonic bonding of gold and aluminium wires.

DIMENSIONS in inches (millimeters)



SERIES	POWER DISSIPATION	DIMENSIONS		
		A	B	C
SA	0.5W	1.5	1.5	0.2
SB	2W	3	3	0.4
SC	6W	5	5	0.5

ELECTRICAL SPECIFICATIONS

Ohmic Values and Associated Tolerance:

$0.05\Omega \leq R < 0.2\Omega \pm 5\%$
 $0.2\Omega \leq R < 0.5\Omega \pm 2\%$
 $0.5\Omega \leq R < 1\Omega \pm 1\%$
 higher values and higher tolerances on request

Power Dissipation at + 70°C: SA: 0.5W
 SB: 2W
 SC: 6W

Temperature Coefficient: $\pm 100\text{ppm}/^\circ\text{C}$
 $\pm 50\text{ppm}/^\circ\text{C}$ on request

Noise: - 35dB max.

Low ohmic value chip resistors are also available with solderable or weldable wraparound terminations.

For standard sizes see our data sheet P Document Number: 53017 and ask us about performance.

MECHANICAL SPECIFICATIONS

Substrate: Alumina

Resistive Element: Ni Cr

Glassivation: Ta_2O_5

Bonding Pads: gold

Backside Metallization: on request Ni Au

ENVIRONMENTAL SPECIFICATIONS

Operating

Temperature Range: - 55°C to + 125°C

Storage Temperature: - 55°C to + 155°C

ORDERING INFORMATION

S SERIES	A TYPE	100 TEMPERATURE COEFFICIENT IN ppm/°C	OR 25 OHMIC VALUE	$\pm 1\%$ TOLERANCE
	A	K = $\pm 100\text{ppm}/^\circ\text{C}$		F = $\pm 1\%$
	B	H = $\pm 50\text{ppm}/^\circ\text{C}$		G = $\pm 2\%$
	C	on request		J = $\pm 5\%$
				S = special